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Dated: June 22, 2005 Signature: Daryl K. Neff
(Daryl K. Neff)

Docket No.: TESSERA 3.0-306 II CIP I
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Warner et al.

Application No.: 10/783,314

Group Art Unit: 2826

Filed: February 20, 2004

Examiner: B. P. Sandvik

For: HIGH-FREQUENCY CHIP PACKAGES

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

It is respectfully requested that the references listed on the enclosed form be made of record and considered with respect to the above-referenced U.S. patent application. Submission of the present Information Disclosure Statement should not be taken as an admission that the cited references are legally available prior art or that the same are pertinent or material.

In the event that any fee is due in connection with the present Information Disclosure Statement, the Commissioner is hereby authorized to charge the same to our Deposit Account No. 12-1095.

Dated: June 22, 2005

Respectfully submitted,

By Daryl K. Neff
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